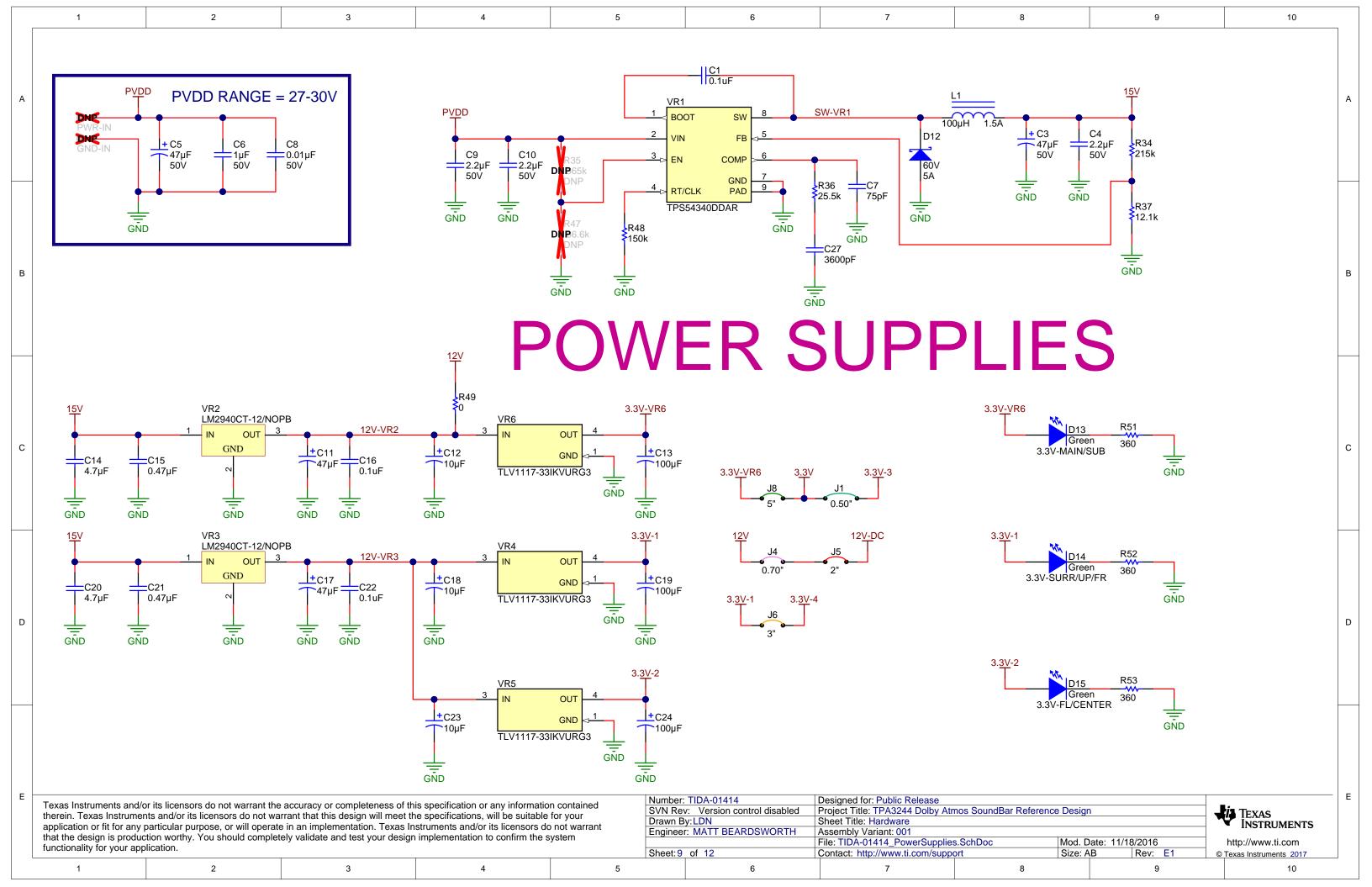
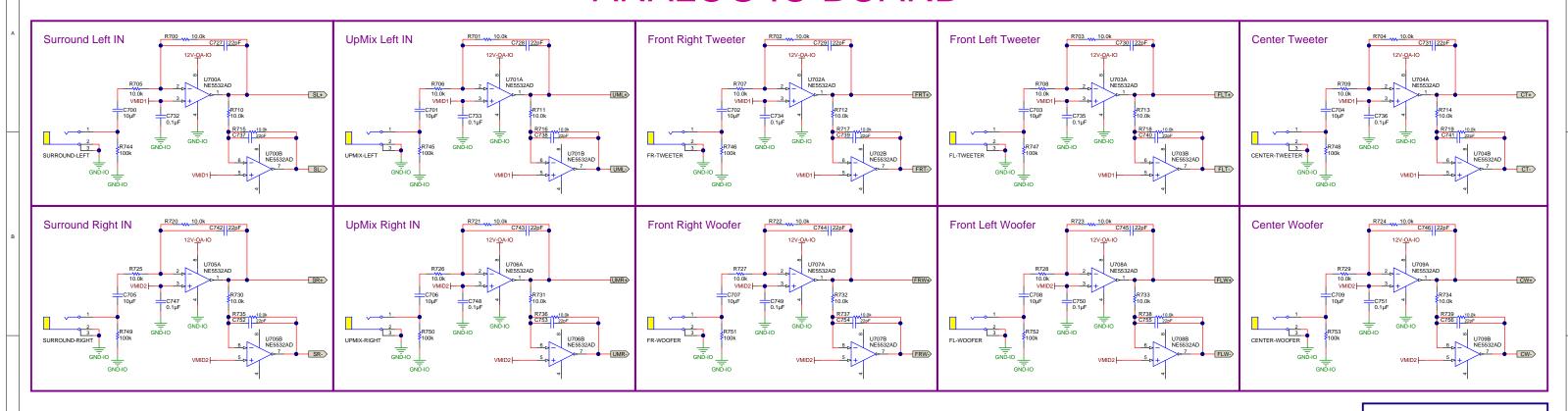
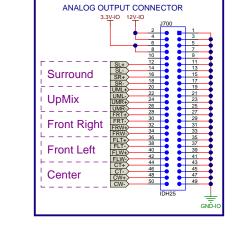


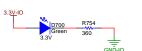
SUBWOOFER CHANNEL R600 C2 22pF C600 100 10.0k C603 10µF C602 0.1µF C604 0.1µF 10µF 10µF -C607 100pF 100k U600 NE5532AD R605 를 GND — GND GND 를 GND GND GND 1000pF OUTLP > 10 10µF R619 100k OUTLN 11 SUBOUT C610 R607 R609 R608 12<u>V-</u>OA 26 SCK 27 BCK 31 LRCK GND SCK6 BCK6 LRCK6 를 GND C612 R620 100pF 100k R610 10.0k NE5532AD 2.2µF MISO(GPIO1)/ADR1/FMT GND 22 GPIO2/ADR2/GPO CAPM -16 VCOM/DEMP 10µF VNEG 9 C613 2.2μF 18 MC/SCL/ATT1 MOSI/SDA/ATT2 를 GND 2 C616 0.1μF 를 GND 25 GPIO6/FLT GPIO5/ATT0 **ADDRESS** NC 29 NC 30 20 GPIO4/MAST 21 GPIO3/AGNS <u>12V</u> **SELECT** AGND -23 MODE1 MS/MODE2 10.0k 10.0k CPGND _C617 GND 10µF DGND GND GND GND GND PCM5252RHBR J600 0.70" BCK6 LRCK6 **12S** DIN2 SCK6 SDA6 I2C SCL6 TIDA-01414 Project Title: TPA3244 Dolby Atmos SoundBar Reference Design Number: TIDA-01414 Rev: E1 Sheet Title: Main Schematic Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not SVN Rev: Version control disabled Assembly Variant: 001 Drawn By:LDN File: TIDA-01414_SubWooferChannel.SchDoc warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its Drawn By:LDN Engineer: MATT BEARDS http://www.ti.com licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

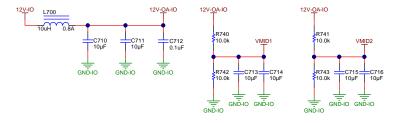


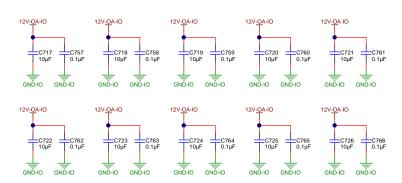
ANALOG IO BOARD

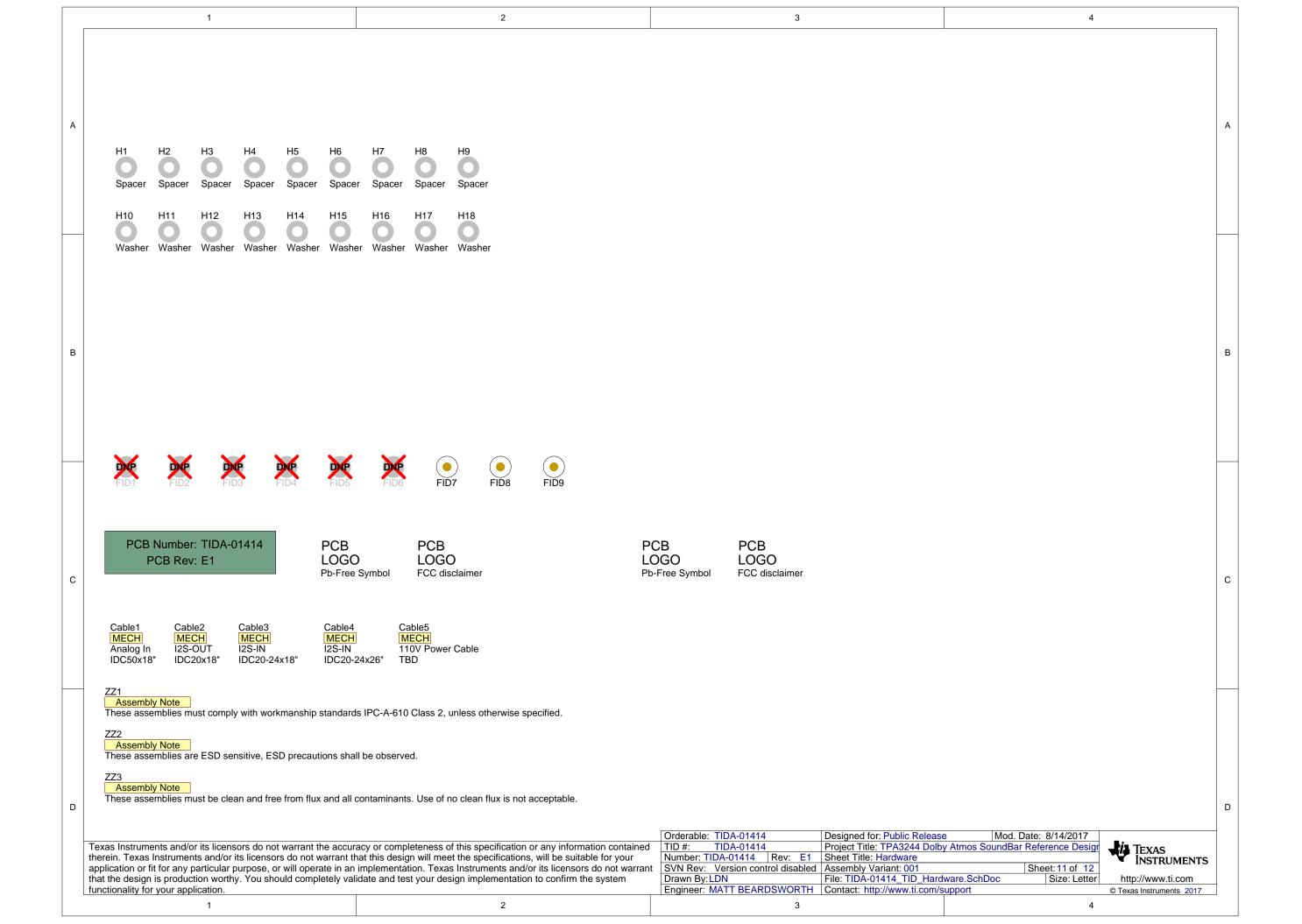












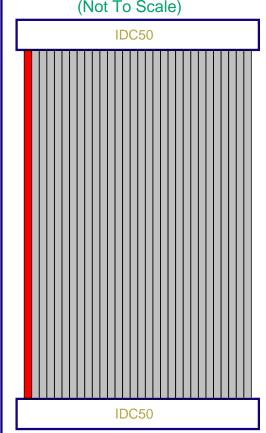
CABLE ASSEMBLIES

Cable 1 **Analog Input Cable** IDC50x18"

Digi-Key Part# H3CCS-5018G-ND (Cable Assembly)

No Instructions for Cable Assembly

Assembled Cable (Not To Scale)

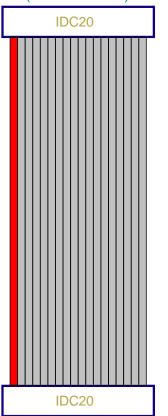


Cable 2 **I2S-OUT** IDC20x18"

Digi-Key Part# H3CCS-2018G (Cable Assembly)

No Instructions

Assembled Cable (Not To Scale)



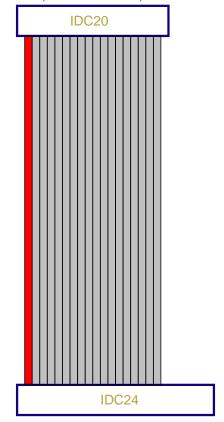
Cable 3 I2S-IN IDC20-24x18"

Digi-Key Part#s H3CCS-2018G-ND (Cbl Assy) HHKC24S-ND (IDC Connector)

Instructions for Cable Assembly

- 1. Cut One Connector Leaving Max Ribbon
- 2. Crimp 24 Pin IDC Connector To Open End, Aligning Pin1 to Pin1

Assembled Cable (Not To Scale)



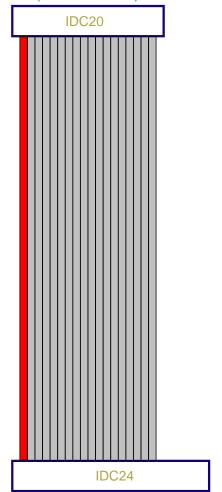
Cable 4 I2S-IN IDC20-24x26"

Digi-Key Part#s H3CCS-2036G-ND (Cbl Assy) HHKC24S-ND (IDC Connector)

Instructions for Cable Assembly

- 1. Cut One Connector off, Cut Cable Length = 26"
- 2. Crimp 24 Pin IDC Connector To Open End, Aligning Pin1 to Pin1

Assembled Cable (Not To Scale)

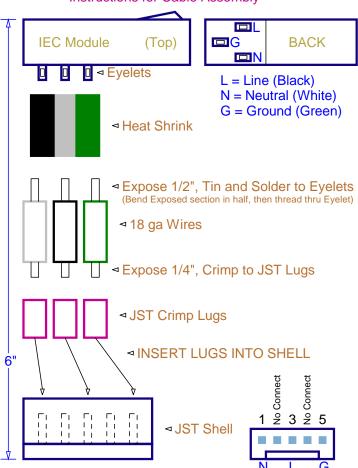


110V Power Cable JST to Lugs Digi-Key Part#s Q307-ND (IEC Power Module) COLORED HEAT SHRINK (Any Vendor) 18ga Alpha Wire, Series 3055 (Black, White and Green) 455-1186-ND (JST 5 Pin Shell) Shell Crimp Pins (TI Will Supply These) Assembled Cable + Module

Cable 5

(Not To Scale) (Pin Positioning Moved for Clarity)

Instructions for Cable Assembly



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